

# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS122A – DECEMBER 1983 – REVISED JANUARY 1995

- Bidirectional Bus Transceivers in High-Density 20-Pin Packages
- Inverting Logic
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

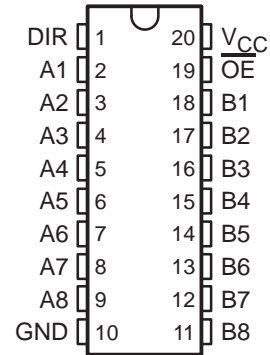
## description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending upon the level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so that the buses are effectively isolated.

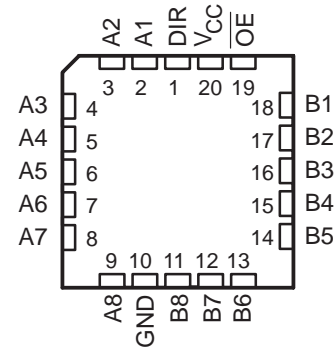
The -1 version of the SN74ALS640B is identical to the standard version, except that the recommended maximum  $I_{OL}$  for the -1 version is increased to 48 mA. There is no -1 version of the SN54ALS640B.

The SN54ALS640B and SN54AS640 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74ALS640B and SN74AS640 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54ALS640B, SN54AS640 . . . J PACKAGE  
SN74ALS640B, SN74AS640 . . . DW OR N PACKAGE  
(TOP VIEW)



SN54ALS640B, SN54AS640 . . . FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	$\overline{B}$ data to A bus
L	H	$\overline{A}$ data to B bus
H	X	Isolation

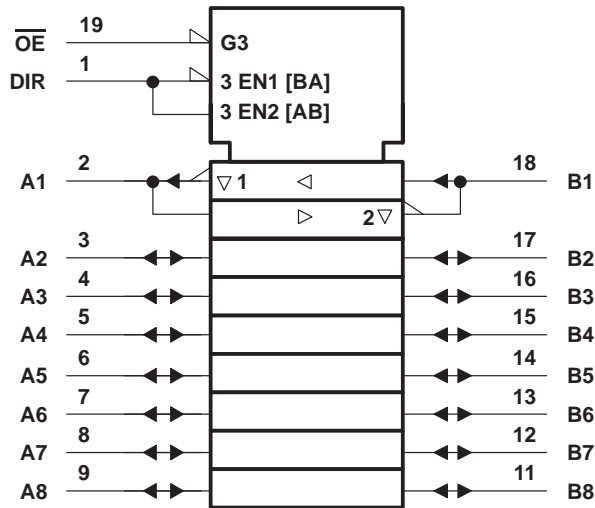
# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640

## OCTAL BUS TRANSCEIVERS

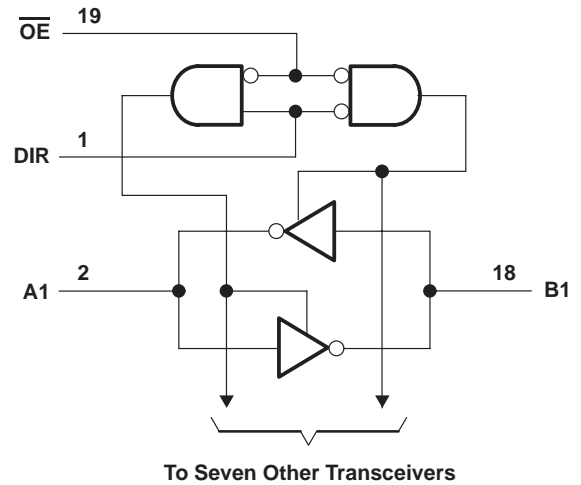
### WITH 3-STATE OUTPUTS

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#### logic symbol†



#### logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$ : All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, $T_A$ : SN54ALS640B	-55°C to 125°C
SN74ALS640B	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

	SN54ALS640B			SN74ALS640B			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$ Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$ High-level input voltage	2			2			V
$V_{IL}$ Low-level input voltage			0.7			0.8	V
$I_{OH}$ High-level output current			-12			-15	mA
$I_{OL}$ Low-level output current			12			24	mA
						48§	
$T_A$ Operating free-air temperature	-55		125	0		70	°C

§ Applies only to the -1 version and only if  $V_{CC}$  is between 4.75 V and 5.25 V

# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		SN54ALS640B		SN74ALS640B		UNIT		
			MIN	TYP†	MAX	MIN		TYP†	MAX
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$		-1.5		-1.5		V		
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $I_{OH} = -0.4\text{ mA}$		$V_{CC} - 2$		$V_{CC} - 2$		V		
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.2	2.4	3.2			
		$I_{OH} = -12\text{ mA}$	2						
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 12\text{ mA}$	0.25	0.4	0.25	0.4	V		
		$I_{OL} = 24\text{ mA}$			0.35	0.5			
		$I_{OL} = 48\text{ mA}^\ddagger$			0.35	0.5			
$I_I$	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 7\text{ V}$		0.1		mA		
	A or B ports		$V_I = 5.5\text{ V}$		0.1				
$I_{IH}$	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 2.7\text{ V}$		20		$\mu\text{A}$		
	A or B ports§				20				
$I_{IL}$	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 0.4\text{ V}$		-0.1		mA		
	A or B ports§				-0.1				
$I_{O}^\parallel$	$V_{CC} = 5.5\text{ V}$ , $V_O = 2.25\text{ V}$		-20	-112	-30	-112	mA		
$I_{CC}$	$V_{CC} = 5.5\text{ V}$		Outputs high		19	50	19	45	mA
			Outputs low		27	60	27	55	
			Outputs disabled		28	55	28	50	

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ Applies only to the -1 version and only if  $V_{CC}$  is between 4.75 V and 5.25 V

§ For I/O ports, the parameters  $I_{IH}$  and  $I_{IL}$  include the off-state output current.

¶ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $C_L = 50\text{ pF}$ , $R_1 = 500\ \Omega$ , $R_2 = 500\ \Omega$ , $T_A = \text{MIN to MAX}^\#$				UNIT
			SN54ALS640B		SN74ALS640B		
			MIN	MAX	MIN	MAX	
$t_{PLH}$	A or B	B or A	2	14	2	11	ns
$t_{PHL}$			2	13	2	10	
$t_{PZH}$	$\overline{OE}$	A or B	4	25	4	21	ns
$t_{PZL}$			5	27	5	24	
$t_{PHZ}$	$\overline{OE}$	A or B	2	12	2	10	ns
$t_{PLZ}$			3	20	3	15	

# For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640

## OCTAL BUS TRANSCEIVERS

### WITH 3-STATE OUTPUTS

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$ : All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, $T_A$ : SN54AS640	-55°C to 125°C
SN74AS640	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN54AS640			SN74AS640			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.8			0.8	V
$I_{OH}$	High-level output current			-12			-15	mA
$I_{OL}$	Low-level output current			48			64	mA
$T_A$	Operating free-air temperature	-55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS640			SN74AS640			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IK}$	$V_{CC} = 4.5$ V, $I_I = -18$ mA			-1.2			-1.2	V
$V_{OH}$	$V_{CC} = 4.5$ V, $I_{OH} = -2$ mA	$V_{CC} - 2$						V
	$V_{CC} = 4.5$ V to 5.5 V, $I_{OH} = -2$ mA				$V_{CC} - 2$			
	$V_{CC} = 4.5$ V	$I_{OH} = -3$ mA	2.4	3.2		2.4	3.2	
		$I_{OH} = -12$ mA	2.4					
$V_{OL}$	$V_{CC} = 4.5$ V	$I_{OL} = 48$ mA	0.3	0.55			V	
		$I_{OL} = 64$ mA				0.35		0.55
$I_I$	Control inputs	$V_{CC} = 5.5$ V	$V_I = 7$ V			0.1	mA	
	A or B ports		$V_I = 5.5$ V			0.1		
$I_{IH}$	Control inputs	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V			20	$\mu$ A	
	A or B ports§					70		70
$I_{IL}$	Control inputs	$V_{CC} = 5.5$ V,	$V_I = 0.4$ V			-0.5	mA	
	A or B ports§					-0.75		-0.75
$I_{O}^{\parallel}$	$V_{CC} = 5.5$ V, $V_O = 2.25$ V			-50		-150	mA	
$I_{CC}$	$V_{CC} = 5.5$ V	Outputs high		37	58		37	58
		Outputs low		78	123		78	123
		Outputs disabled		51	80		51	80

‡ All typical values are at  $V_{CC} = 5$  V,  $T_A = 25^\circ$ C.

§ For I/O ports, the parameters  $I_{IH}$  and  $I_{IL}$  include the off-state output current.

¶ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .



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**OCTAL BUS TRANSCEIVERS**  
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**switching characteristics (see Figure 1)**

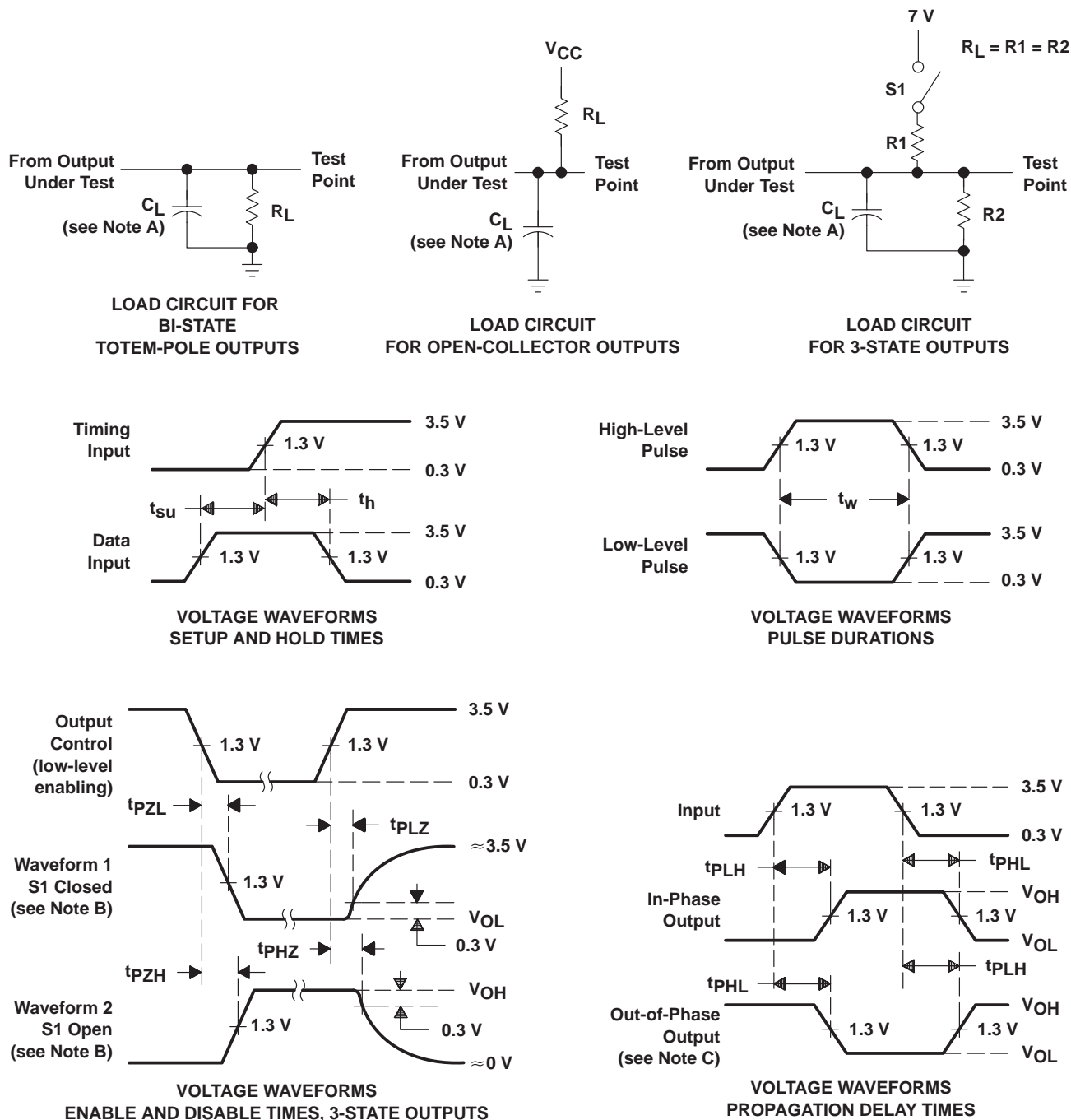
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54AS640		SN74AS640		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	B or A	1	8	2	7	ns
t <sub>PHL</sub>			1	7	2	6	
t <sub>PZH</sub>	$\overline{OE}$	A or B	2	10	2	8	ns
t <sub>PZL</sub>			2	12	2	10	
t <sub>PHZ</sub>	$\overline{OE}$	A or B	2	9	2	8	ns
t <sub>PLZ</sub>			2	16	2	13	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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## PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
 D. All input pulses have the following characteristics:  $PRR \leq 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.  
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
5962-88727012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
5962-8872701RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-8872701SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
5962-89553012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8955301RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-8955301SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI	
SN54ALS640BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN54AS640J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN74ALS640B-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640B-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640B-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640B-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640B-1DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640B-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640B-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS640B-1N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	
SN74ALS640B-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS640B-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640B-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640B-1NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74ALS640BDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640BDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640BDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640BDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640BN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS640BNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS640BNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640BNSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS640BNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS640N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS640NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS640NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS640NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS640NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS640BFK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
SNJ54ALS640BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS640BW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	
SNJ54AS640FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54AS640J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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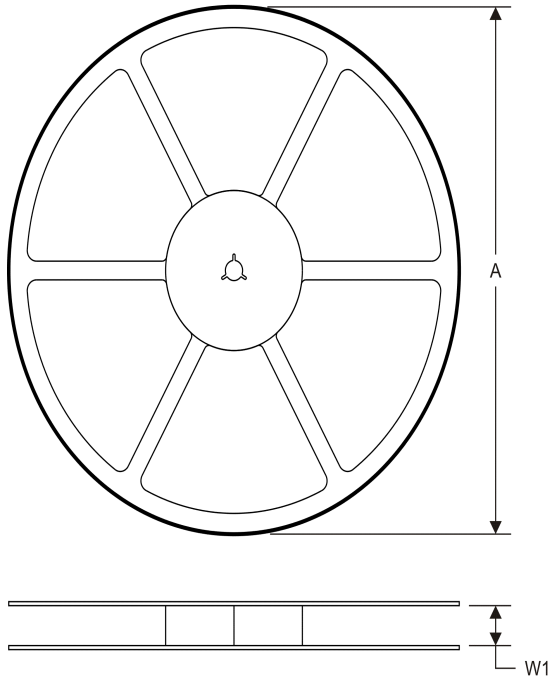
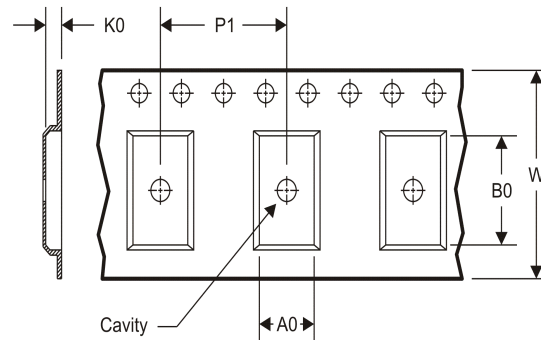
**OTHER QUALIFIED VERSIONS OF SN54ALS640B, SN54AS640, SN74ALS640B, SN74AS640 :**

● Catalog: [SN74ALS640B](#), [SN74AS640](#)

● Military: [SN54ALS640B](#), [SN54AS640](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS640B-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS640B-1NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS640BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS640BNSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AS640NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

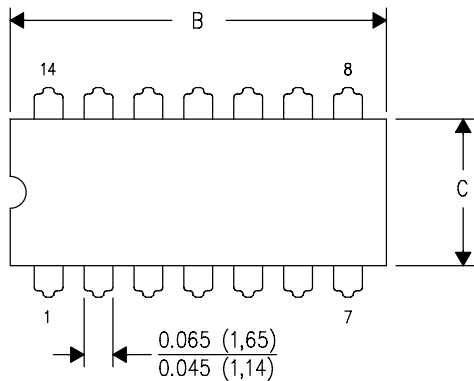

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS640B-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS640B-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS640BDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS640BNSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS640NSR	SO	NS	20	2000	367.0	367.0	45.0

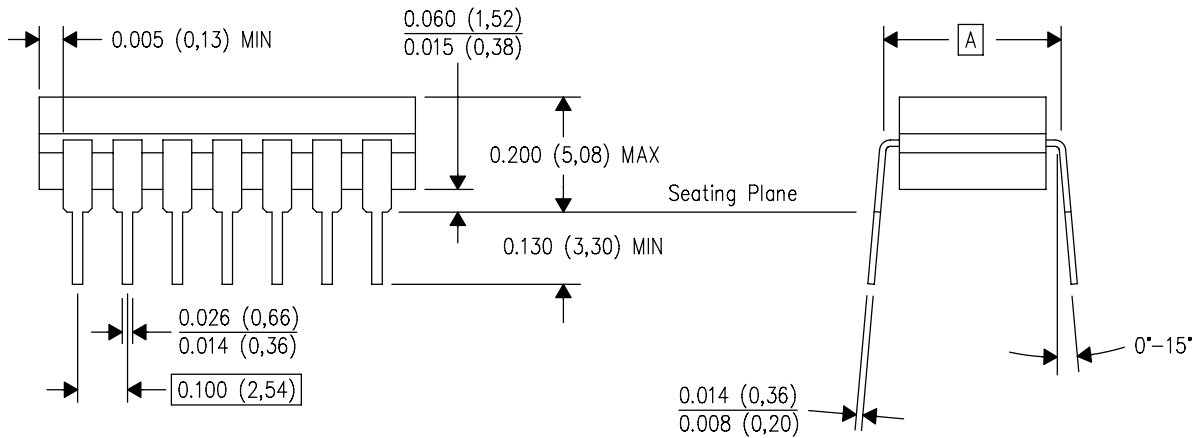
# J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

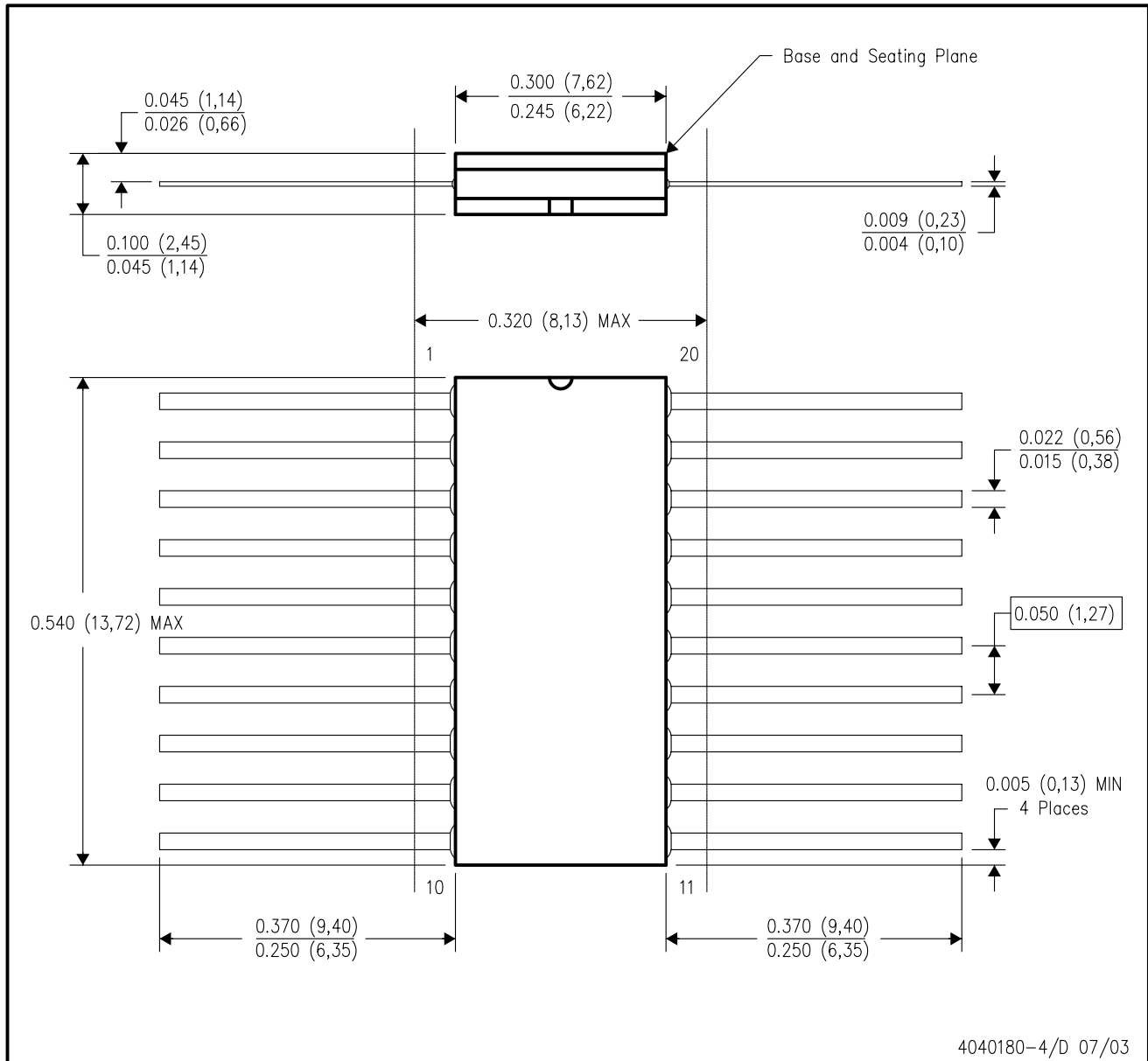


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

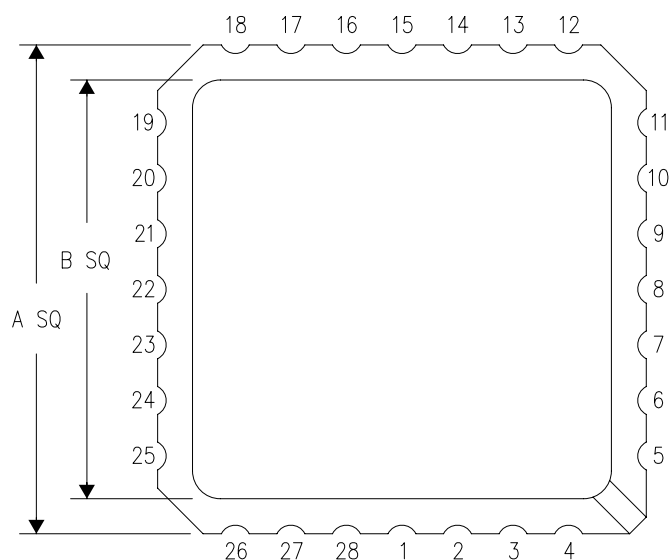


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

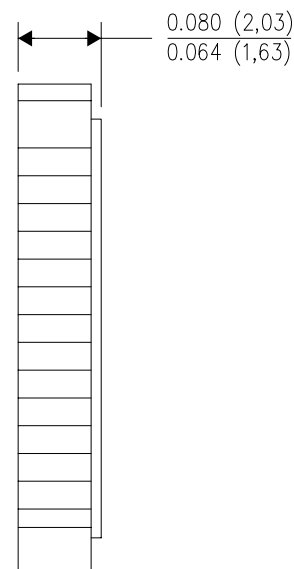
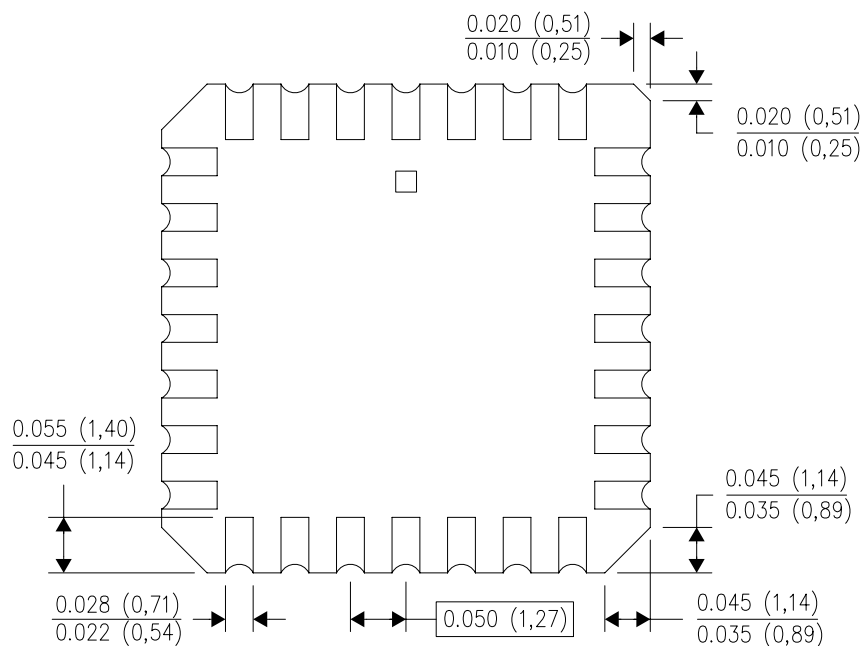
FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



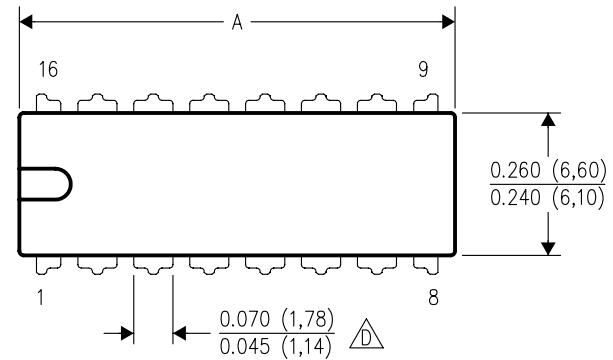
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

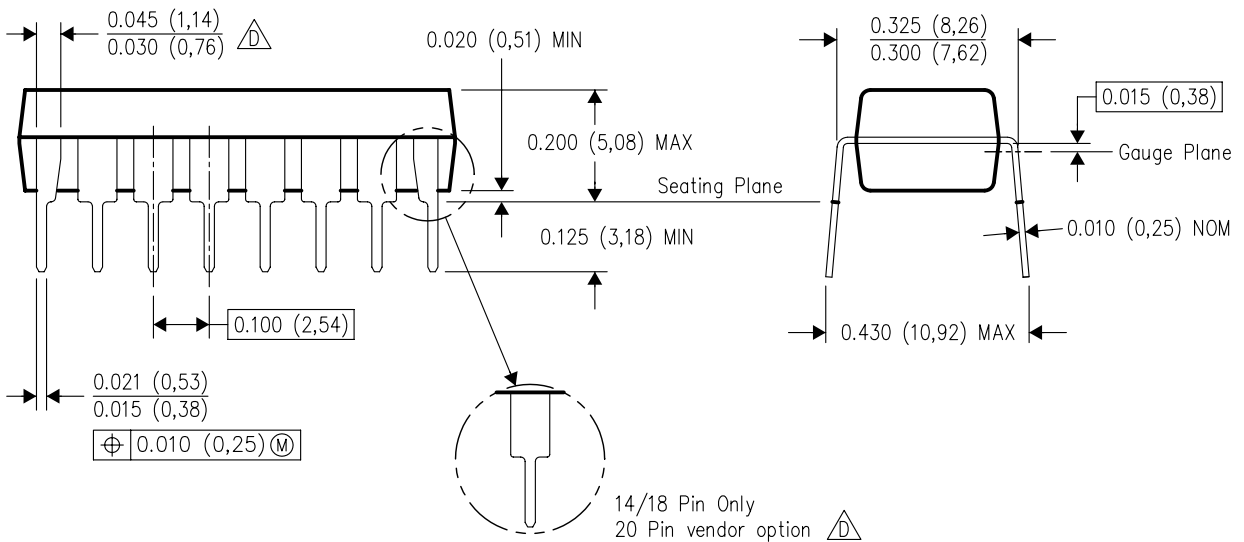
N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



DIM	PINS **			
	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

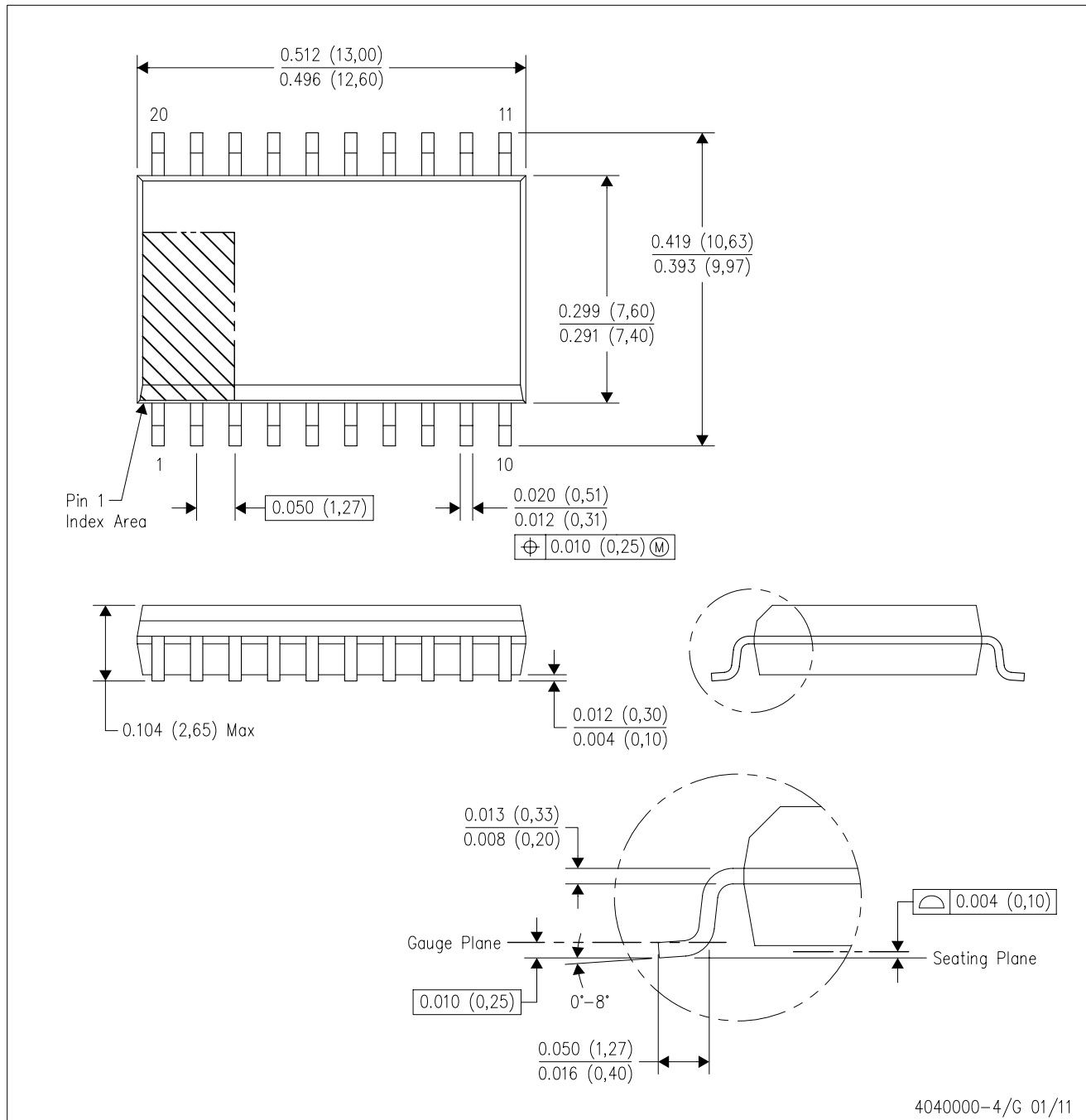


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

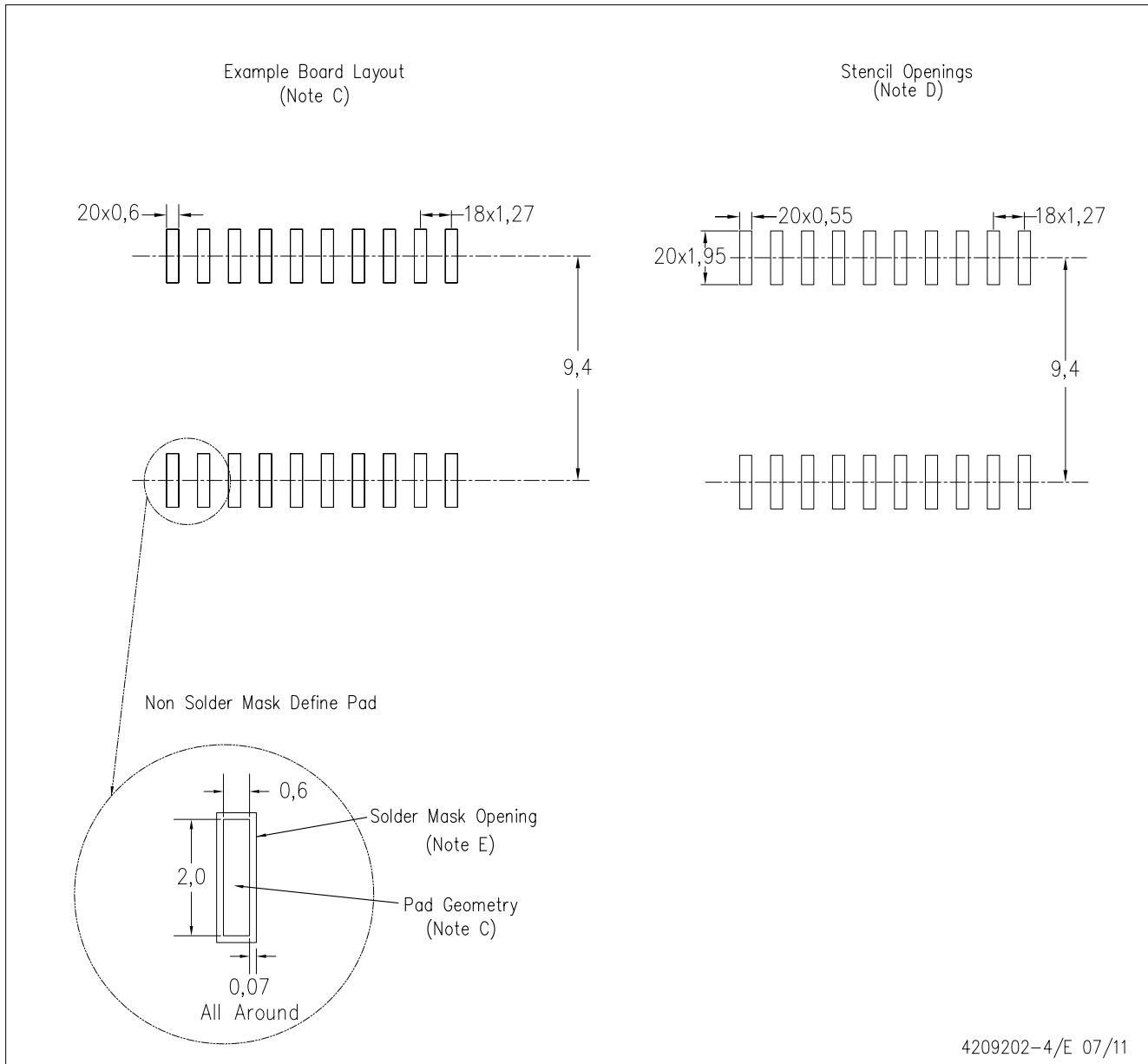
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/E 07/11

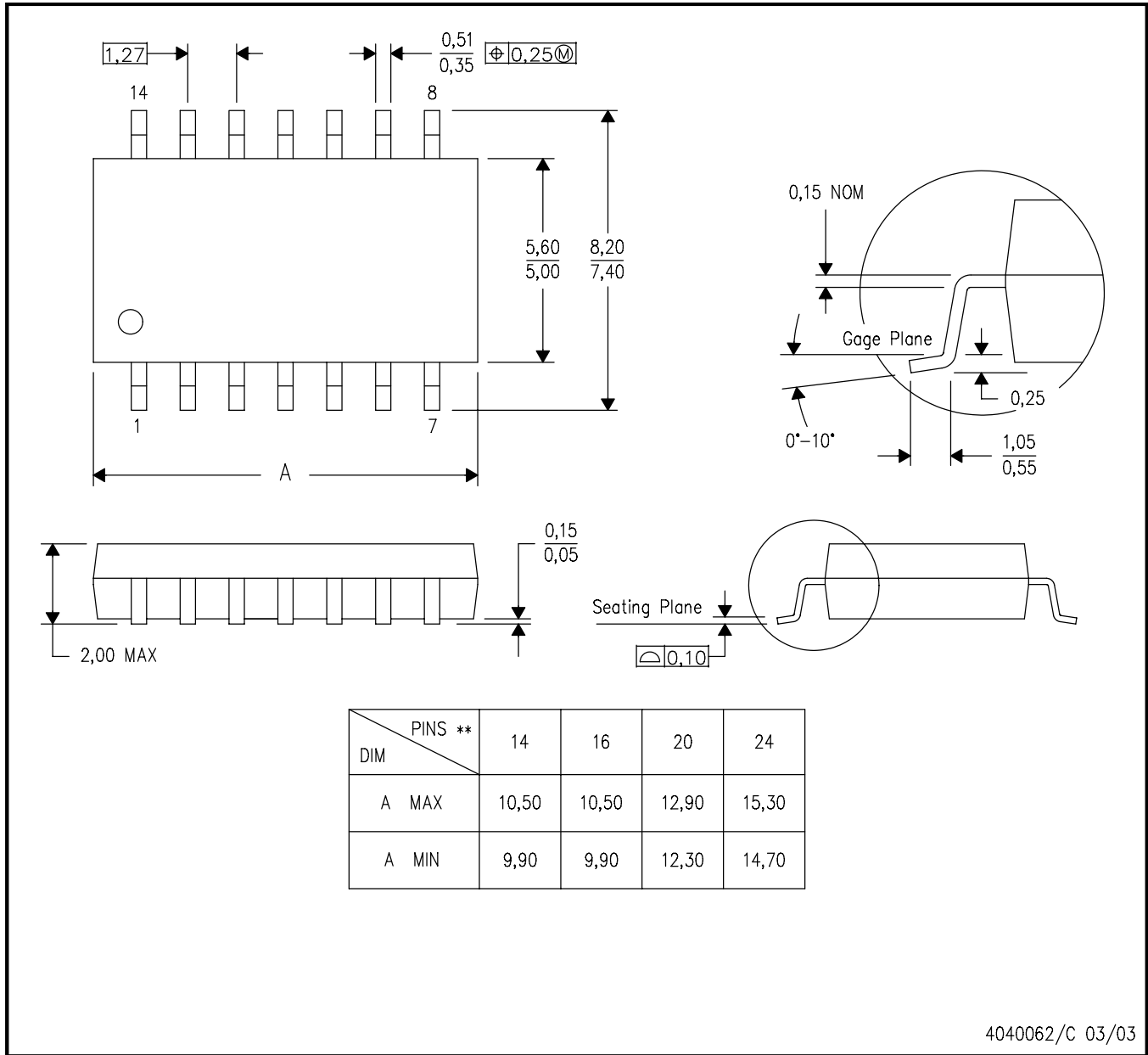
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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